

A2 12. (Amended) A method according to Claim 7, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

A3 13. (New) A method according to Claim 8, wherein said step of cleaning outer surfaces of the electronic component chips comprises a process of grinding outer surfaces of electronic component chips.

14. (New) A method according to Claim 8, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

15. (New) A method according to Claim 9, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

16. (New) A method according to Claim 10, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid

A3 17. (New) A method according to Claim 11, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

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